

Atty. Dkt. No. 039153-0649 (H0982)

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- 1-10. (Cancelled)
11. (Original) A method of making an SMOS structure containing a plurality of transistors, the method comprising:
 - providing a first semiconductor substrate including a base layer, a strained semiconductor layer, and a first oxide layer;
 - attaching a second semiconductor substrate including a second oxide layer to the first oxide layer; and
 - separating the base layer from the first substrate.
12. (Original) The method of claim 11, wherein a semiconductor/germanium layer is above the strained semiconductor layer.
13. (Original) The method of claim 12, further comprising:
 - providing an aperture in the semiconductor/germanium layer.
14. (Original) The method of claim 13, further comprising:
 - doping the strained semiconductor layer through the aperture.
15. (Original) The method of claim 15, wherein the doping step forms source and drain extensions.
16. (Original) The method of claim 13, further comprising:
 - providing a gate conductor in the aperture.
17. (Original) The method of claim 16, further comprising:

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separating the gate conductor from the silicon/germanium layer with a spacer material.

18. (Original) The method of claim 12, further comprising: siliciding the semiconductor/germanium layer.
19. (Original) The method of claim 11, wherein the attaching step is a hydrogen bonding step.
20. (New) A method of manufacturing of an integrated circuit, the integrated circuit comprising a first wafer and a second wafer, the first wafer including a silicon germanium layer, a strained silicon layer, and a first insulating layer, the second wafer including a substrate and a second insulating layer, the second insulating layer being attached to the first insulating layer, the method comprising steps of:
 - providing the first wafer including base layer, silicon germanium layer, the strained silicon layer, and the first insulating layer;
 - attaching the second wafer to the first wafer; and
 - separating base layer from the first wafer.
21. (New) The method of claim 20 wherein the substrate is a bulk silicon substrate.
22. (New) The method of claim 20, wherein the substrate is a semiconductor material.
23. (New) The method of claim 22, wherein the silicon germanium layer includes a hydrogen breaking interface.
24. (New) The method of claim 20, wherein a channel region is disposed in the strained silicon layer.

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25. (New) The method of claim 24, wherein a source region and a drain region are disposed in the strained silicon layer.

26. (New) The method of claim 25, wherein an aperture is formed in the silicon germanium layer to expose the strained silicon layer.

27. (New) The method of claim 26, wherein a gate structure is provided in the aperture.

28. (New) A method of fabricating a multilayer structure containing a plurality of transistors including strained regions, the multilayer structure comprising a semiconductor/germanium layer, a strained semiconductor layer, a gate dielectric, and a gate conductor including a source and a drain provided below the semiconductor/germanium layer, the semiconductor/germanium layer having an aperture, the gate dielectric above the strained semiconductor layer and within the aperture, the gate conductor being disposed within the aperture, the method comprising:

providing a first substrate including the semiconductor/germanium layer, the strained semiconductor layer, and a first oxide layer;

attaching a second substrate including a second oxide layer to the first oxide layer; providing the aperture within the semiconductor/germanium layer; and

providing the gate dielectric and gate conductor within the aperture.

29. (New) The method of claim 28, further comprising:
providing a spacer in the aperture separating the semiconductor/germanium layer and the gate conductor.

30. (New) The method of claim 28, further comprising:

providing silicide layer above the semiconductor/germanium layer.